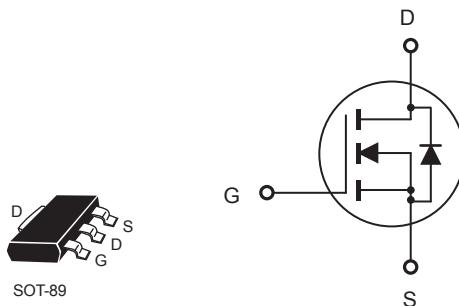


N-Channel Enhancement Mode Field Effect Transistor**FEATURES**

- 60V, 4.6A, $R_{DS(ON)} = 90m\Omega$ @ $V_{GS} = 10V$.
 $R_{DS(ON)} = 110m\Omega$ @ $V_{GS} = 4.5V$.
- High dense cell design for extremely low $R_{DS(ON)}$.
- Rugged and reliable.
- Lead free product is acquired.
- SOT-89 package.

**ABSOLUTE MAXIMUM RATINGS** $T_A = 25^\circ C$ unless otherwise noted

Parameter	Symbol	Limit	Units
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current-Continuous	I_D	4.6	A
Drain Current-Pulsed ^a	I_{DM}	18.4	A
Maximum Power Dissipation	P_D	3	W
Operating and Store Temperature Range	T_J, T_{Stg}	-55 to 150	$^\circ C$

Thermal Characteristics

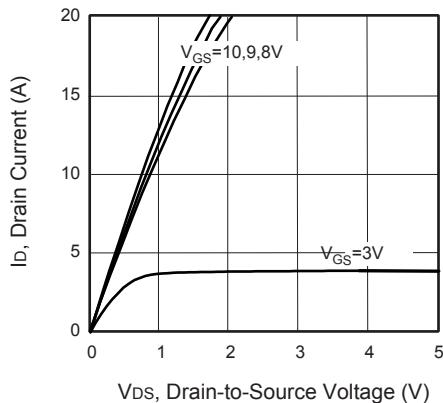
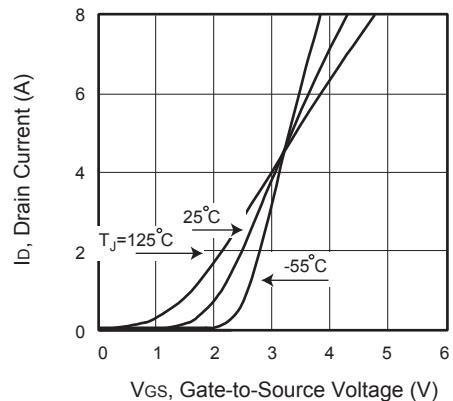
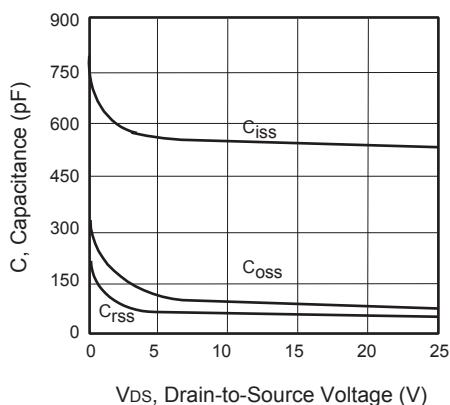
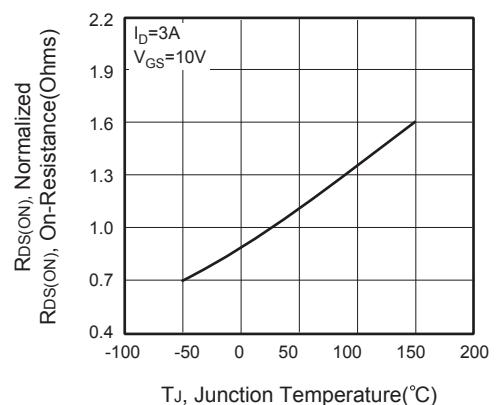
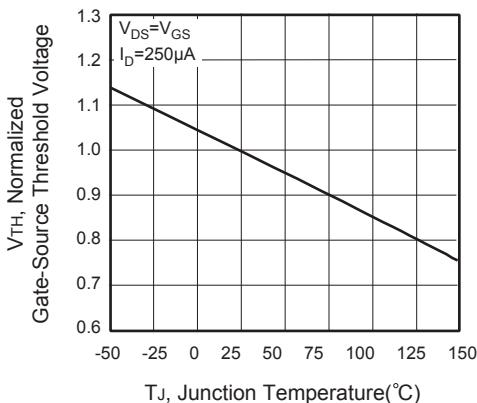
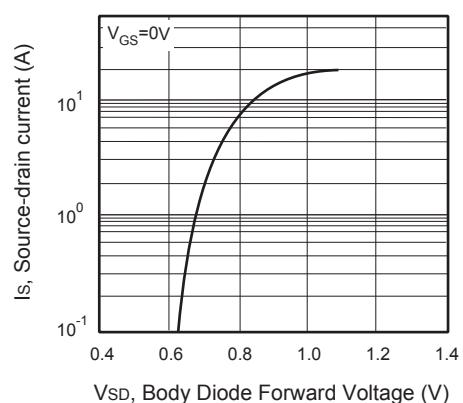
Parameter	Symbol	Limit	Units
Thermal Resistance, Junction-to-Ambient ^b	$R_{\theta JA}$	42	$^\circ C/W$



CEA6426

Electrical Characteristics $T_A = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	60			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 60\text{V}, V_{\text{GS}} = 0\text{V}$			1	μA
Gate Body Leakage Current, Forward	I_{GSSF}	$V_{\text{GS}} = 20\text{V}, V_{\text{DS}} = 0\text{V}$			100	nA
Gate Body Leakage Current, Reverse	I_{GSSR}	$V_{\text{GS}} = -20\text{V}, V_{\text{DS}} = 0\text{V}$			-100	nA
On Characteristics						
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{GS}} = V_{\text{DS}}, I_D = 250\mu\text{A}$	1		3	V
Static Drain-Source On-Resistance	$R_{\text{DS(on)}}$	$V_{\text{GS}} = 10\text{V}, I_D = 3\text{A}$ $V_{\text{GS}} = 4.5\text{V}, I_D = 2.4\text{A}$		64	90	$\text{m}\Omega$
Dynamic Characteristics^d						
Input Capacitance	C_{iss}	$V_{\text{DS}} = 25\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0 \text{ MHz}$		530		pF
Output Capacitance	C_{oss}			70		pF
Reverse Transfer Capacitance	C_{rss}			50		pF
Switching Characteristics^d						
Turn-On Delay Time	$t_{\text{d(on)}}$	$V_{\text{DD}} = 30\text{V}, I_D = 1\text{A}, V_{\text{GS}} = 10\text{V}, R_{\text{GEN}} = 6\Omega$		9	18	ns
Turn-On Rise Time	t_r			4	8	ns
Turn-Off Delay Time	$t_{\text{d(off)}}$			28	56	ns
Turn-Off Fall Time	t_f			3	6	ns
Total Gate Charge	Q_g	$V_{\text{DS}} = 30\text{V}, I_D = 4.5\text{A}, V_{\text{GS}} = 10\text{V}$		13	17	nC
Gate-Source Charge	Q_{gs}			1		nC
Gate-Drain Charge	Q_{gd}			4		nC
Drain-Source Diode Characteristics and Maximum Ratings						
Drain-Source Diode Forward Current ^b	I_S				3	A
Drain-Source Diode Forward Voltage ^c	V_{SD}	$V_{\text{GS}} = 0\text{V}, I_S = 3\text{A}$			1	V
Notes :						
a.Repetitive Rating : Pulse width limited by maximum junction temperature.						
b.Surface Mounted on FR4 Board, $t \leq 10 \text{ sec.}$						
c.Pulse Test : Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.						
d.Guaranteed by design, not subject to production testing.						
□						

**Figure 1. Output Characteristics****Figure 2. Transfer Characteristics****Figure 3. Capacitance****Figure 4. On-Resistance Variation with Temperature****Figure 5. Gate Threshold Variation with Temperature****Figure 6. Body Diode Forward Voltage Variation with Source Current**

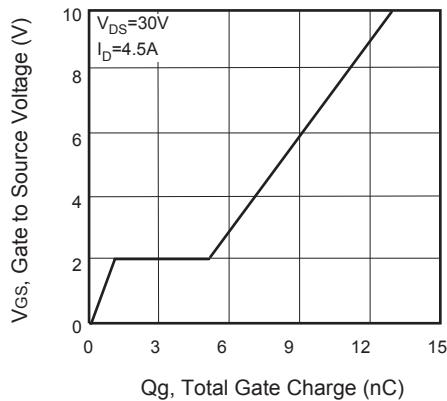


Figure 7. Gate Charge

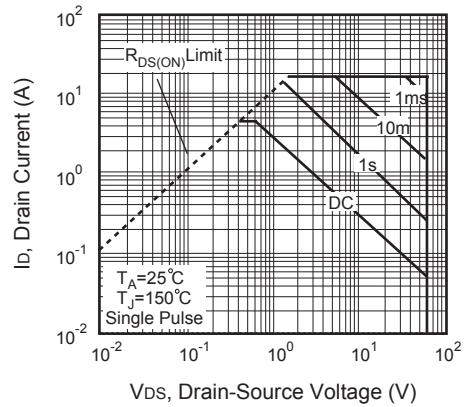


Figure 8. Maximum Safe Operating Area

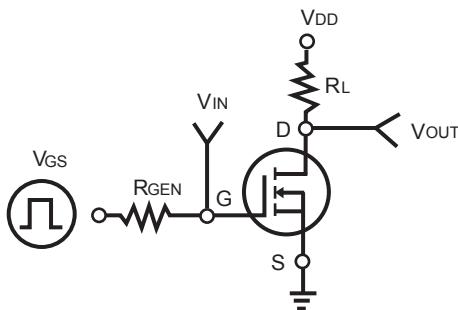


Figure 9. Switching Test Circuit

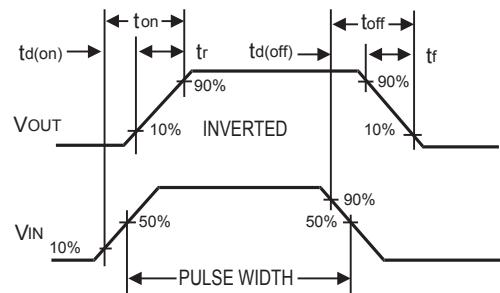


Figure 10. Switching Waveforms

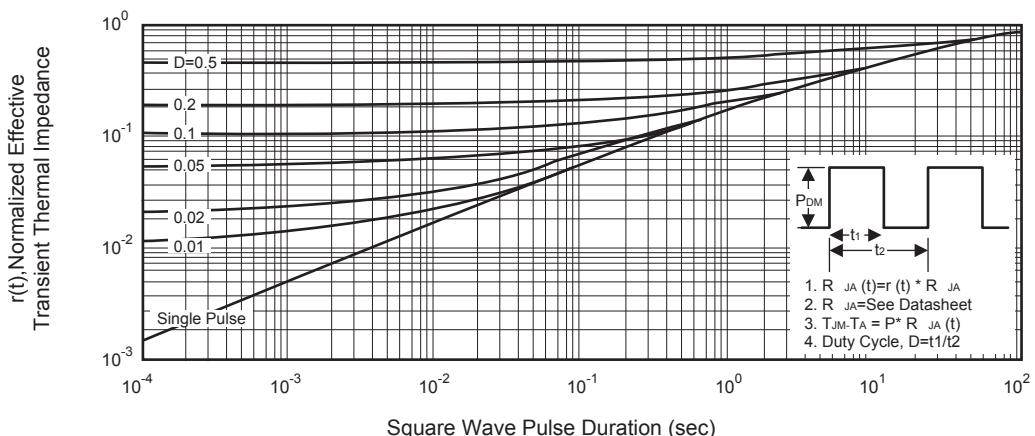


Figure 11. Normalized Thermal Transient Impedance Curve